

WHAT IS CLAIMED IS:

1. A substrate for a device package comprising:
  - a lower portion of a package;
  - an intermediate metalization layer on a top surface of said lower portion;
  - an upper portion of said package on said top surface of said lower portion, a corner portion of said intermediate metalization layer remaining visible beyond the extent of said upper portion for indicating an orientation of said substrate.
2. The substrate of Claim 1, said lower and upper portions comprising a ceramic.
3. The substrate of Claim 1, said lower portion comprising a layered ceramic portion containing electrical interconnections.
4. The substrate of Claim 1, said visible corner portion comprising a plating on said visible corner portion.
5. The substrate of Claim 1, comprising an electrical device electrically connected to portions of said metalization layer.
6. The substrate of Claim 1, comprising an electrical device electrically connected to portions of said metalization layer, said visible corner portion electrically isolated from said portions of said metalization layer electrically connected to said device.
7. The substrate of Claim 1, comprising an electrical device and a lid enclosing said device between said lid and said substrate.
8. The substrate of Claim 1, said upper portion having a void over said visible corner region of said metalization layer, said void allowing visibility to said metalization layer.
9. The substrate of Claim 8, said void used to mechanically position said substrate.
10. A method of forming a device package comprising:

providing a lower portion of a package;

providing an intermediate metalization layer on a top surface of said lower portion;

providing an upper portion of said package on said top surface of said lower portion, a corner portion of said intermediate metalization layer remaining visible beyond the extent of said upper portion for indicating an orientation of said substrate.

11. The method of Claim 10, said providing a lower portion comprising providing a lower ceramic portion.
12. The method of Claim 10, said providing an upper portion comprising providing an upper ceramic portion.
13. The method of Claim 10, said providing a lower portion comprising providing a layered ceramic portion containing electrical interconnections.
14. The method of Claim 10, comprising plating said visible corner portion.
15. The method of Claim 10, comprising attaching a device to said substrate and electrically connecting portions of said metalization layer to said device.
16. The method of Claim 11, comprising electrically isolating said visible corner portion from portions of said metalization layer electrically connected to said device.
17. The method of Claim 10, comprising a lid enclosing said device between said lid and said substrate.
18. The method of Claim 10, said providing an upper portion comprising providing an upper portion having a void over said visible corner region of said metalization layer, said void allowing visibility to said metalization layer.

19. The method of Claim 18, comprising using said void to mechanically position said substrate.

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